

S-Band, GaN/SiC, RF Power Transistor

2.9 - 3.15 GHz | 75 W | 55% Efficiency typ | 14dB Gain typ | 45 V | 100 μs Pulse Length, 10% Duty Cycle

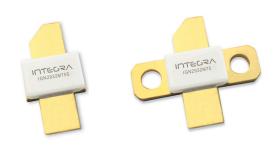
IGN2932M75 and IGN2932M75S are high power GaN-on-SiC RF power transistors that have been designed to suit the unique needs of modern radar systems. They supply a minimum of 75W of peak output power, with typically 14dB of gain and 55% efficiency. They operate from a 45 V supply voltage. For optimal thermal efficiency, the transistors are housed in a metal-based package with an epoxysealed ceramic lid.

FEATURES

- GaN on SiC HEMT Technology
- Output Power 75W
- Pre-matched Input and Output Impedances
- High Efficiency 55% typical
- 100% RF Tested under 100µs, 10% duty cycle pulse conditions
- RoHS and REACH Compliant

APPLICATIONS

S-band Radar Systems



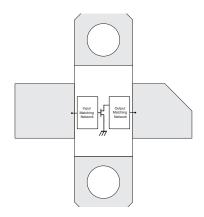


Table 1. RF Electrical Characteristics (Case temperature = 30 °C unless otherwise stated)

Parameter	Symbol	Min	Тур	Мах	Units	Test Conditions
RF Output Power	P _{OUT, RF}	75	100	160	W	
Gain	G	12.7	14	16	dB	
Drain Efficiency	η	50	55	75	%	$P_{IN} = 4W$
Pulse Droop	D	-0.5	-0.2	+0.3	dB	f = 2.9, 3.025, 3.15 GHz 100μs pulse length, 10% duty cycle
Input Return Loss	IRL	7	15	20	dB	$V_{\rm DS} = 45V, I_{\rm DQ} = 20mA$
VSWR Mismatch Stability	VSWR-S	2:1				
VSWR Withstand	VSWR-LMT	3:1				

Note: Consult Integra Technologies Application Note 001 for information on how RF output power and pulse droop are measured.



Table 2. Absolute Maximum Ratings (Not Simultaneous)

Parameter	Symbol	Value	Units	Test Conditions
DC Drain-Source Voltage	V _{DS}	140	V	25 °C
DC Gate-Source Voltage	V _{GS}	-8 to +1	V	25 °C
DC Drain Current	I _D	12	А	25 °C
DC Gate Current	Ι _G	12	mA	25 °C
RF Input Power	P _{re,in}	4	W	25 °C
Operating Channel Temperature	Т _{сн}	-55 to +200	٥C	
Storage Temperature	T _{stg}	-55 to +150	٥C	
Soldering Temperature	T _{SOLDER}	260 for 10s	٥C	

Note: Operation outside the limits given in this table may cause permanent damage to the transistor

Table 3. DC Electrical Characteristics (Case temperature = 25 °C unless otherwise stated)

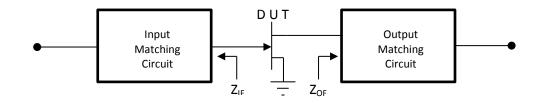
Parameter	Symbol	Min	Тур	Мах	Units	Test Conditions
Gate Pinch-Off Voltage	V _P	-5.0			V	$V_{_{\rm DS}} = 45$ V, $I_{_{\rm DS}} = 1$ mA
Quiescent Gate Voltage	V _Q		-2.8		V	$V_{_{\rm DS}} = 45$ V, $I_{_{\rm DS}} = 20$ mA

Table 4. Thermal Resistance (Case temperature = 30 °C unless otherwise stated)

Parameter	Symbol	Min	Тур	Max	Units	Test Conditions
Peak Thermal Resistance, Channel to Case	R _{th}		0.96		⁰C/W	$P_{_{DISS}} = 82W$ 100µs pulse length, 10% duty cycle $V_{_{DS}} = 45V$

Table 5. Matching Circuit Impedances (Case temperature = 25 °C unless otherwise stated)

Frequency (GHz)	Z	Z _{of}	Units	Test Conditions
2.9	2.7 - j 6.7	3.0 - j 3.7	Ω	Р _{оит} = 75W
3.025	2.9 - j 6.2	3.2 - j 3.3	Ω	100 μs Pulse length, 10% Duty Cycle $V_{_{DS}}=45V\text{, I}_{_{DQ}}=20\text{mA}$
3.15	2.5 - j 6.2	3.2 - j 3.4	Ω	





TYPICAL PERFORMANCE

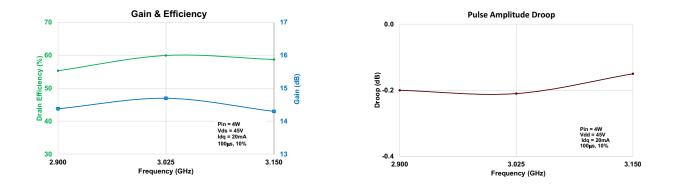
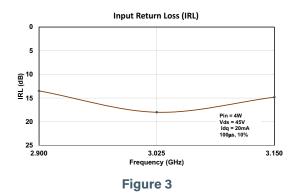


Figure 1

Figure 2







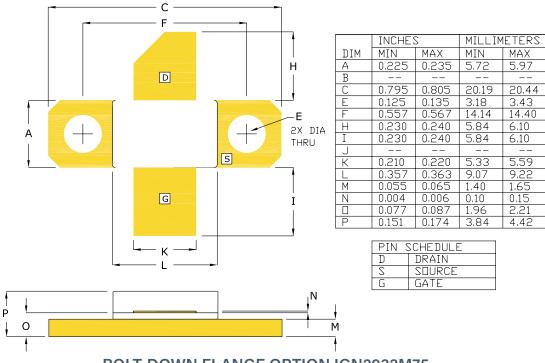
TEST FIXTURE

Bill of Materials for IGN2932M75 Test Fixture

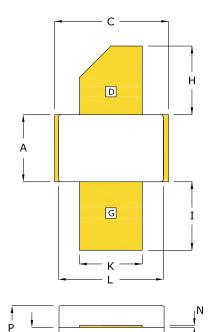
Designator	Description	Quantity
C1, C4, C11	CAP 0.1µF, 0805, 100V	3
C2, C5, C6	CAP 27pF, 0805, 50V	3
C3 ,C9	CAP 10µF, 2220, 50V, X7R	2
C7, C8	CAP 12pF, Edge Mount	2
C10	CAP 5.6pF, Edge Mount	1
C12	CAP 1µF, 1206, 100V	1
L1, L2	IND FB, 120 OHM, 0805, 5A	2
L3	IND 5.5nH, 1508	1
R1, R2, R2, R4	RES 5.1 OHM, 0805	4
PC Board Type	ROGERS 4350B-03011, 30mils, 1/1 oz Cu	2



PACKAGE PL32A1 DIMENSIONS



BOLT-DOWN FLANGE OPTION IGN2932M75



S

	INCHES	S	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
А	0.225	0.235	5.72	5.97
В				
С	0.380	0,400	9.65	10.16
E				
F				
Н	0.230	0.240	5.84	6.10
Ι	0.230	0.240	5.84	6.10
J				
К	0,210	0.250	5,33	5,59
L	0.357	0.363	9.07	9.22
М	0.055	0.065	1.40	1.65
Ν	0.004	0,006	0.10	0.15
	0.077	0.087	1.96	2.21
Ρ	0.151	0,174	3,84	4.42

PIN S	SCHEDULE
D	DRAIN
S	SOURCE
G	GATE

EARLESS FLANGE OPTION IGN2932M75S

Μ

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ESD Rating

Parameter	Rating	Standard
ESD Human Body Model (HBM)	TBD	ESDA/JEDEC JS-001-2012
ESD Charged Device Model (CDM)	TBD	JEDEC JESD22-C101F
Moisture Sensitivty Level (MSL)	Unlimited Shelf Life	IPC/JEDEC J-STD-020

RoHS Compliance

Integra Technologies, Inc declares that its GaN and LDMOS Transistor Products comply with EU Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU.

REACH Compliance

Integra Technologies supports EU Regulation number 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) as these apply to Integra semiconductor products, development tools, and shipping packaging.

In support of the REACH regulation, Integra will:

- Inform customers and recipients of Integra product if they contain any substances that are of very high concern (SVHC) per the European Chemical Agency (ECHA) website.
- •Notify ECHA if any Integra product that contains any SVHCs which exceed guidelines for REACH chemicals by weight per part number and for total content weight per year for all products produced in or imported to the European market.
- •Cease shipments of product containing REACH Annex XIV substances until authorization has been obtained.
- •Cease shipment of product containing REACH Annex XVII chemicals when restrictions apply.

Integra has evaluated its materials, BOMs, and product specifications and product and has determined that this transistor conforms to all REACH and SVHC regulations and guidelines. Integra has implemented actions and control programs that will assure continued compliance.

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DEFINITIONS:

DATA SHEET STATUS

Advanced Specification - This data sheet contains Advanced specifications.

Preliminary Specification - This data sheet contains specifications based on preliminary measurements and data.

Final Specification - This data sheet contains final product specifications.

MAXIMUM RATINGS Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.

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